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E-CLOUD in PS2, PS+, SPS+: update Feb. 2007

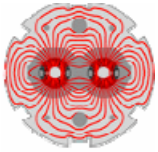
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(presented by M. Venturini)

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ECL2 -- CERN, 1-2 March 2007

*(Initial talk presented at CARE-HHH-APD LHC-LUMI-06,
IFIC, Valencia, 16-20 October 2006)*



Summary

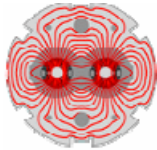


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- ⌞ Results for ecloud build-up in LHC injector upgrades (PS2, PS+, SPS, SPS+,...)
 - Bunch spacings $t_b = 12.5, 25, 50$ and 75 ns
 - Obtained with code **POSINST**
 - Only in a **dipole** bending magnet, during **1st injected batch**

- ⌞ Initial results (PPT file) were presented by MF at LUMI06
 - Coarse integration time step ($\Delta t = 0.1-0.3$ ns) for expediency
- ⌞ Present (new) results have $\Delta t = 0.02-0.07$ ns
 - These are now published in the LUMI06 proceedings (see also <http://mafurman.lbl.gov/LBNL-61925.pdf>)

- ⌞ Basic conclusion:
 - **New results much more favorable** vis-à-vis heat load (roughly speaking, factor 5-20, depending on the case)
 - Caveat: time step $\Delta t = 0.02-0.07$ ns believed to be adequate, but not methodically checked



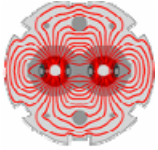
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Input parameter table

(from LBNL-61925, based on FZ's "psplustcparameters" and "lhcupgradeparameters")



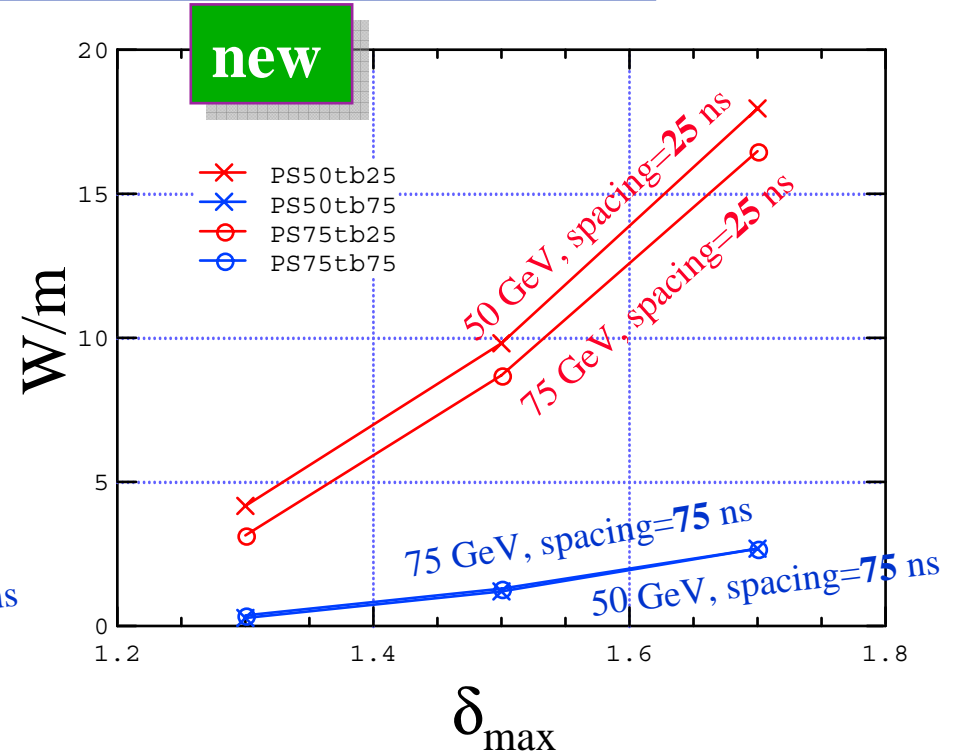
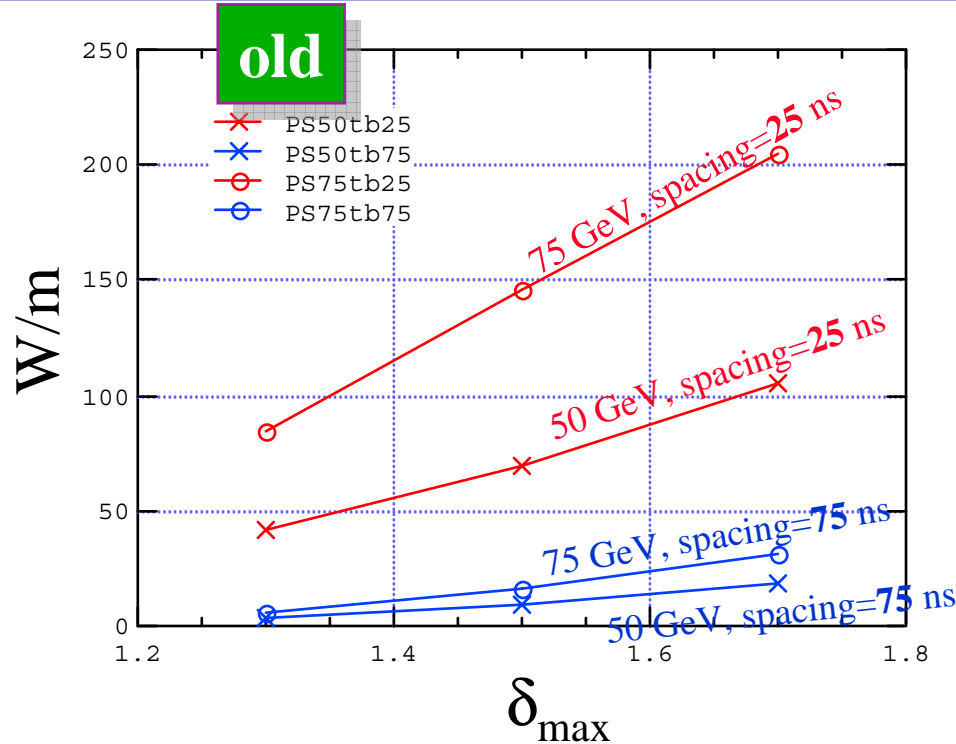
Case	Our notation	E_b GeV	B T	(a, b) cm	N_b 10^{11}	t_b ns	(σ_x, σ_y) mm	σ_z cm	profile
PS2, 50 GeV extr.	PS50tb12p5	50	1.8	(8, 4)	2	12.5	(1, 0.9)	57.3	gauss.
	PS50tb25	50	1.8	(8, 4)	4	25	(1, 0.9)	93.5	gauss.
	PS50tb50	50	1.8	(8, 4)	5.4	50	(1, 0.9)	104	flat
	PS50tb75	50	1.8	(8, 4)	6.6	75	(1, 0.9)	104	flat
PS+, 75 GeV extr.	PS75tb12p5	75	2.7	(8, 4)	2	12.5	(0.8, 0.8)	50.5	gauss.
	PS75tb25	75	2.7	(8, 4)	4	25	(0.8, 0.8)	83.5	gauss.
	PS75tb50	75	2.7	(8, 4)	5.4	50	(0.8, 0.8)	92.3	flat
	PS75tb75	75	2.7	(8, 4)	6.6	75	(0.8, 0.8)	92.3	flat
SPS, 50 GeV inj.	SPS50tb12p5	50	0.225	(7, 2.2)	1.9	12.5	(3.1, 1.6)	14.3	gauss.
	SPS50tb25	50	0.225	(7, 2.2)	3.8	25	(2.8, 1.6)	23.4	gauss.
	SPS50tb50	50	0.225	(7, 2.2)	5.2	50	(3, 1.6)	26.1	flat
	SPS50tb75	50	0.225	(7, 2.2)	6.4	75	(3, 1.6)	26.1	flat
SPS, 75 GeV inj.	SPS75tb12p5	75	0.337	(7, 2.2)	1.9	12.5	(2.4, 1.3)	12.6	gauss.
	SPS75tb25	75	0.337	(7, 2.2)	3.8	25	(2.1, 1.3)	20.9	gauss.
	SPS75tb50	75	0.337	(7, 2.2)	5.2	50	(2.3, 1.3)	23.1	flat
	SPS75tb75	75	0.337	(7, 2.2)	6.4	75	(2.3, 1.3)	23.1	flat
SPS, 450 GeV extr.	SPS450tb12p5	450	2.025	(7, 2.2)	1.9	12.5	(1.2, 0.9)	12	gauss.
	SPS450tb25	450	2.025	(7, 2.2)	3.8	25	(1, 0.5)	12	gauss.
	SPS450tb50	450	2.025	(7, 2.2)	5.2	50	(1, 0.5)	15	flat
	SPS450tb75	450	2.025	(7, 2.2)	6.4	75	(1, 0.5)	15	flat
SPS+, 1 TeV extr.	SPS1000tb12p5	1000	4.5	(6, 2)	1.8	12.5	(0.5, 0.4)	12	gauss.
	SPS1000tb25	1000	4.5	(6, 2)	3.6	25	(0.6, 0.4)	12	gauss.
	SPS1000tb50	1000	4.5	(6, 2)	5.1	50	(0.5, 0.4)	15	flat
	SPS1000tb75	1000	4.5	(6, 2)	6.2	75	(0.5, 0.4)	15	flat
SPS+a, 50 GeV inj.	SPSpa50tb12p5	50	0.225	(6, 2)	1.9	12.5	(3.1, 1.6)	14.3	gauss.
	SPSpa50tb25	50	0.225	(6, 2)	3.8	25	(2.8, 1.6)	23.4	gauss.
	SPSpa50tb50	50	0.225	(6, 2)	5.2	50	(3, 1.6)	26.1	flat
	SPSpa50tb75	50	0.225	(6, 2)	6.4	75	(3, 1.6)	26.1	flat
SPS+b, 75 GeV inj.	SPSpb75tb12p5	75	0.337	(6, 2)	1.9	12.5	(2.4, 1.3)	12.6	gauss.
	SPSpb75tb25	75	0.337	(6, 2)	3.8	25	(2.1, 1.3)	20.9	gauss.
	SPSpb75tb50	75	0.337	(6, 2)	5.2	50	(2.3, 1.3)	23.1	flat
	SPSpb75tb75	75	0.337	(6, 2)	6.4	75	(2.3, 1.3)	23.1	flat



Sample old vs. new results: heat load for PS2 and PS+



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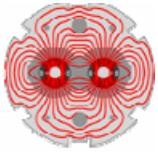


↩ Old: MF talk at LUMI06

— 21 kicks/bunch, or $\Delta t = (6-7) \times 10^{-10}$ s

↩ New: MF paper in LUMI06 proceedings (LBNL-61925)

— 201-251 kicks/bunch, or $\Delta t = (5.5-6.7) \times 10^{-11}$ s



Sample new results: heat load vs. δ_{\max}

(PS, $E_b=50$ or 75 GeV; SPS, $E_b=75$ GeV; $t_b=25, 50, 75$ ns)



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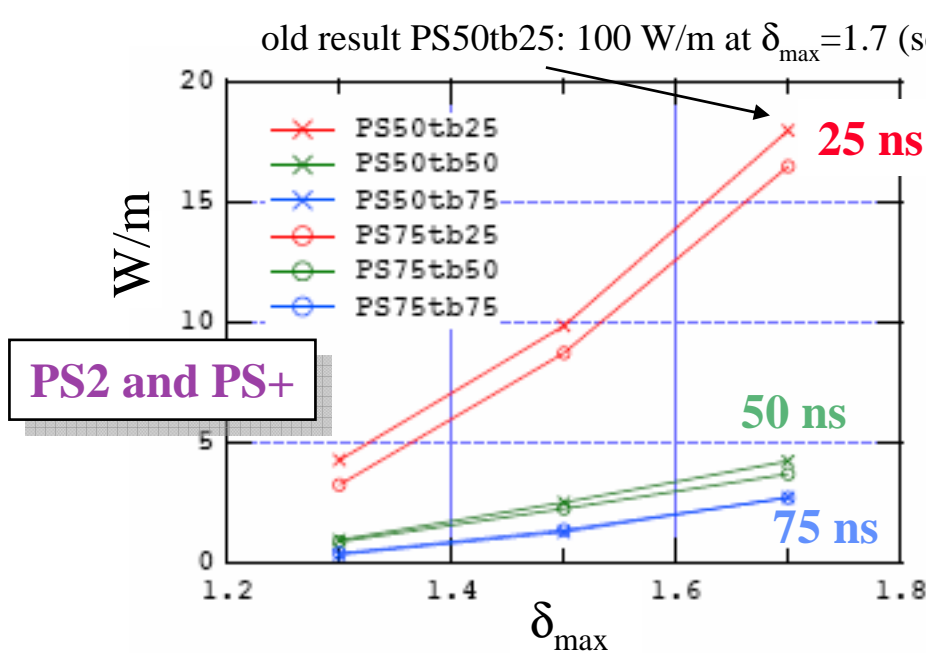


Figure 4: Simulated PS ecloud heat load vs. δ_{\max} for cases PS50 and PS75 (PS2 and PS+ in "psplustcparameters," respectively).

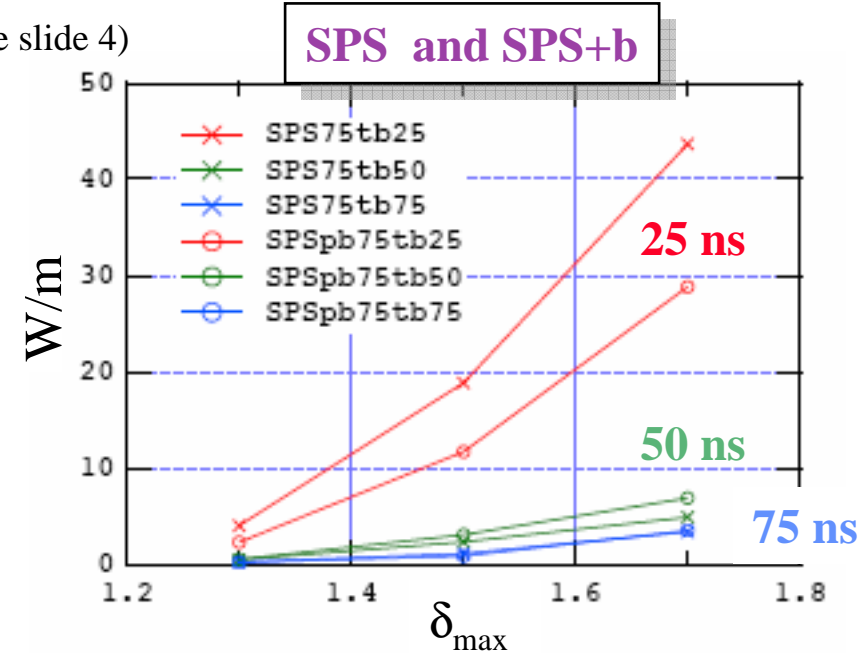
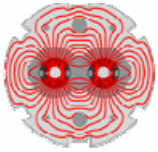


Figure 7: Simulated SPS ecloud heat load vs. δ_{\max} for cases SPS75 and SPSpb75. The only difference between the calculation for these two cases is the transverse chamber size (see text).

- ⊞ Generally, $t_b=50$ and 75 ns is much more favorable than 25 ns
 - But 75 ns not significantly better than 50 ns
- ⊞ SPS $\sim x2$ higher heat load for same E_b , N_b and t_b than PS probably owing to smaller σ_z and smaller chamber size



Sample new results: Cu vs. St.St.



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120-150 W/m for St.St.

PS2 and PS+

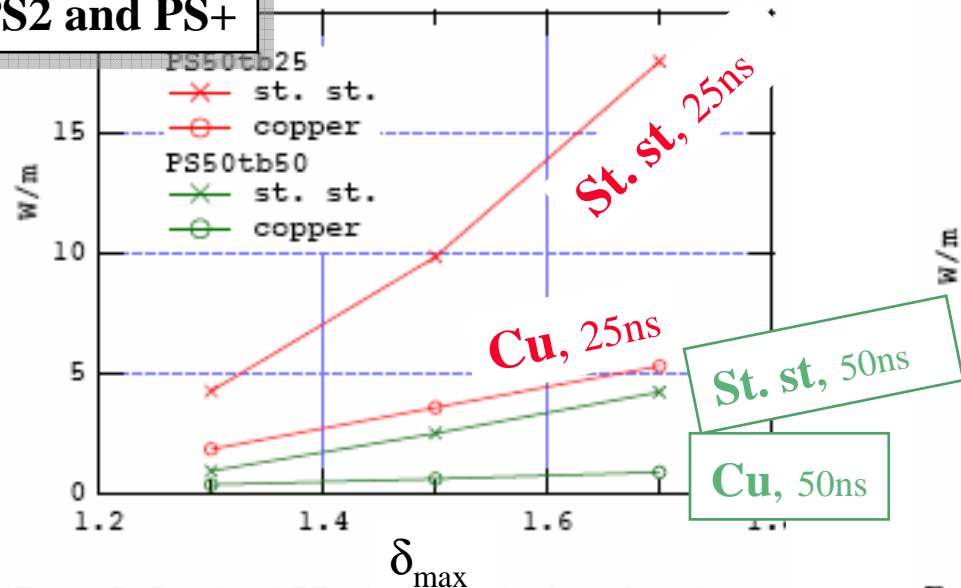


Figure 5: Simulated PS ecloud heat load vs. δ_{max} for case PS50, for copper and stainless steel chamber. The only difference in the calculation for the two cases is the secondary emission energy spectrum of the two metals.

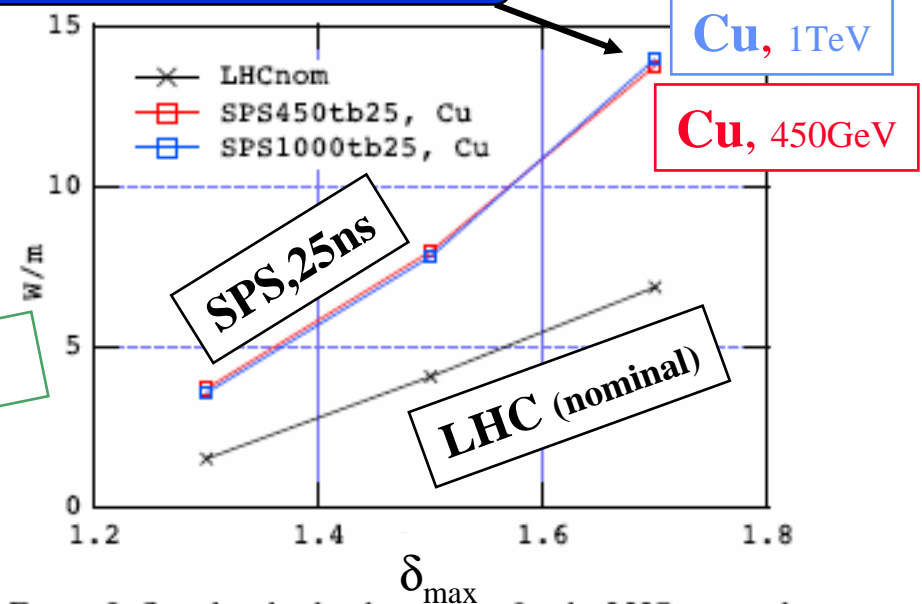
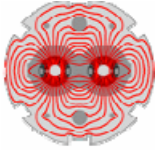


Figure 9: Simulated ecloud heat load for the LHC nominal case and for the SPS+ at $E_b = 450$ and $1,000$ GeV vs. δ_{max} assuming a SEY model for copper. The bunch spacing is $t_b = 25$ ns in all cases (LHC results taken from Fig. 2).

- ⌞ Copper much more favorable than St.St.
 - Owing to smaller rediffused component in SE energy spectrum
 - Subtle mechanism; explained in detail in Sec. IV-B of <http://prst-ab.aps.org/pdf/PRSTAB/v9/i3/e034403>
- ⌞ Caveat: Cu and StSt emission parameters need to be re-measured to confirm this!



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Conclusions



- ⌞ Heat load depends inversely with t_b
 - $t_b=75$ ns is best, closely followed by 50 ns
 - $t_b=50$ ns much better than 25 ns
 - $t_b=12.5$ ns is terrible
- ⌞ Cu (or Cu-coated) chamber much better than St.St.
 - But this conclusion is based on a particular set of measurements of the SE energy spectrum
 - Re-measure energy spectrum in order to verify this conclusion
- ⌞ Not much difference in heat load between gaussian vs. flat long. profile for the LHC, at least for $t_b=50$ ns
- ⌞ Not much difference between PS2 and PS+, nor between SPS50 and SPS+a50, except at high δ_{max} for $t_b=25$ ns
- ⌞ This investigation is limited to heat load in the dipole bends
- ⌞ I feel much more comfortable about the relative rankings than about the absolute values of the heat load